



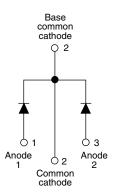
www.vishay.com

Vishay Semiconductors

HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A



TO-247AC



PRODUCT SUMMARY						
Package	TO-247AC					
I _{F(AV)}	2 x 15 A					
V_{R}	600 V					
V _F at I _F	1.7 V					
t _{rr} typ.	19 ns					
T _J max.	150 °C					
Diode variation	Common cathode					

FEATURES

- · Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC-JESD47
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912





ROHS
COMPLIANT
HALOGEN
FREE
Available

BENEFITS

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA30PA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30PA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30PA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage	V_{R}		600	V			
Maximum continuous forward current per leg		T _C = 100 °C	15				
per device	P IF		30	А			
Single pulse forward current	I _{FSM}		150				
Maximum repetitive forward current	I _{FRM}		60				
Maximum navvar dissination	Ь	T _C = 25 °C	74	W			
Maximum power dissipation	P_{D}	T _C = 100 °C	29] vv			
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	°C			



VS-HFA30PA60CPbF, VS-HFA30PA60C-N3

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ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		600	-	-	
Maximum forward voltage		I _F = 15 A		=	1.3	1.7	V
	V_{FM}	I _F = 30 A	See fig. 1	=	1.5	2.0	
		I _F = 15 A, T _J = 125 °C]	=	1.2	1.6	
Maximum reverse		V _R = V _R rated	Soo fig. 2	-	1.0	10	
leakage current	I _{RM}	$T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated	See fig. 2	-	400	1000	μΑ
Junction capacitance	C _T	V _R = 200 V See fig. 3		=	25	50	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	12	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	0 A/μs, V _R = 30 V	-	19	-		
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C		-	42	60	ns	
occ lig. 5, 10	t _{rr2}	T _J = 125 °C	I _F = 15 A	-	70	120		
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	4.0	6.0	А	
See fig. 6	I _{RRM2}	T _J = 125 °C		-	6.5	10		
Reverse recovery charge	Q _{rr1}	T _J = 25 °C	dl _F /dt = 200 A/μs V _B = 200 V	-	80	180	nC	
See fig. 7	Q _{rr2}	T _J = 125 °C	VR = 200 V	-	220	600		
Peak rate of fall of recovery current during t _b See fig. 8	dI _{(rec)M} /dt1	T _J = 25 °C		-	250	-	- A/μs	
	dI _{(rec)M} /dt2	T _J = 125 °C		-	160	-	Ανμδ	

THERMAL-MECHANICAL SPECIFICATIONS PER LEG								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conduction	D		-	-	1.7			
Junction to case, both legs conducting	R _{thJC}		-	-	0.85	12001		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	K/W		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-			
Maint			-	6.0	-	g		
Weight			-	0.21	-	OZ.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-247AC (JEDEC)	HFA30PA60C					

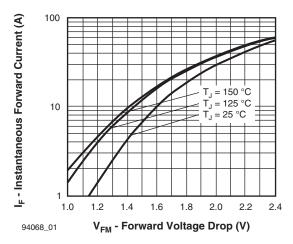


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

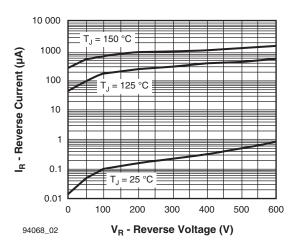


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

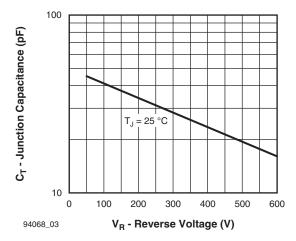


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

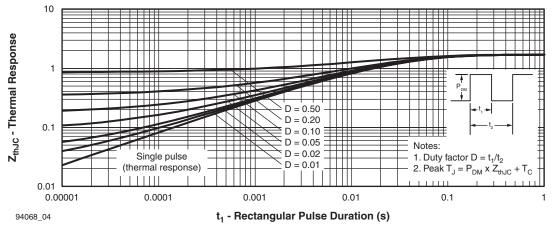


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

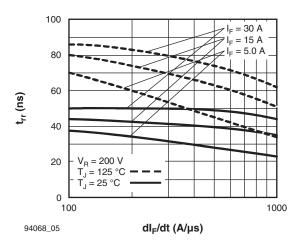


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

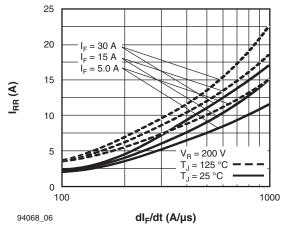


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

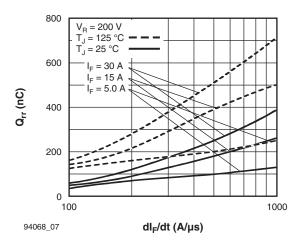


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

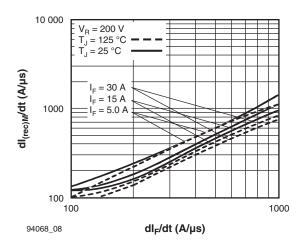


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt (Per Leg)

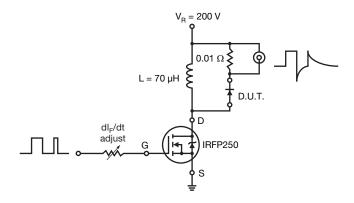
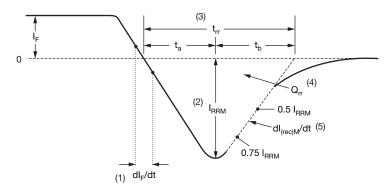


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

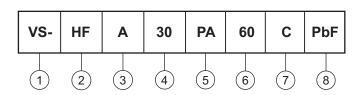
Fig. 10 - Reverse Recovery Waveform and Definitions

VS-HFA30PA60CPbF, VS-HFA30PA60C-N3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - HEXFRED® family

3 - Electron irradiated

4 - Current rating (30 = 30 A)

5 - PA = TO-247AC

6 - Voltage rating: (60 = 600 V)

7 - Circuit configuration

C = Common cathode

8 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

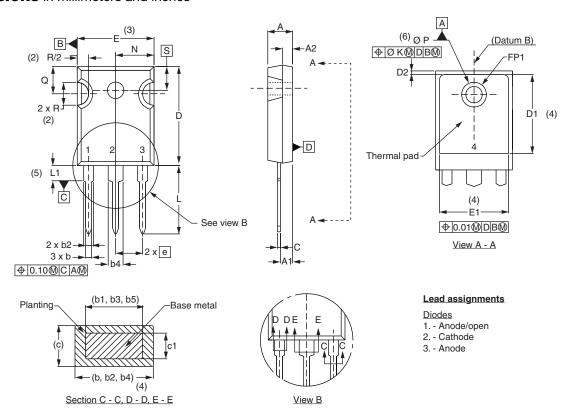
-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-HFA30PA60CPbF	25	500	Antistatic plastic tube					
VS-HFA30PA60C-N3	25	500	Antistatic plastic tube					

LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95223</u>						
Dark mandring information	TO-247ACPbF	www.vishay.com/doc?95226				
Part marking information	TO-247AC-N3	www.vishay.com/doc?95007				
SPICE model		www.vishay.com/doc?95182				



DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.37	0.065	0.094	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.86	0.015	0.034	
c1	0.38	0.76	0.015	0.030	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.72	-	0.540	-	
е	5.46	BSC	0.215	BSC	
FK	2.	2.54		0.010	
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
N	7.62 BSC		0	.3	
ΦР	3.56	3.66	0.14	0.144	
ФР1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	1.78	0.216	
S	5.51	BSC	0.217	'BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



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Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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